



SIP (PIN OUT:1357)



DIP



SMD



SIP (PIN OUT:1267)



HIGH INSULATION (DIP)



HIGH INSULATION (SMD)

FEATURES

- Miniature, cost-effective switching solution.
- Molded construction for compatibility with automatic board processing.
- Completely washable.
- Dip type construction with the same terminal pitch as ICs or TTLs.
- The high sensitivity allows direct driving by TTL, etc.
- Magnetic shield cover is available.

SPECIFICATIONS

● **COIL RATING**

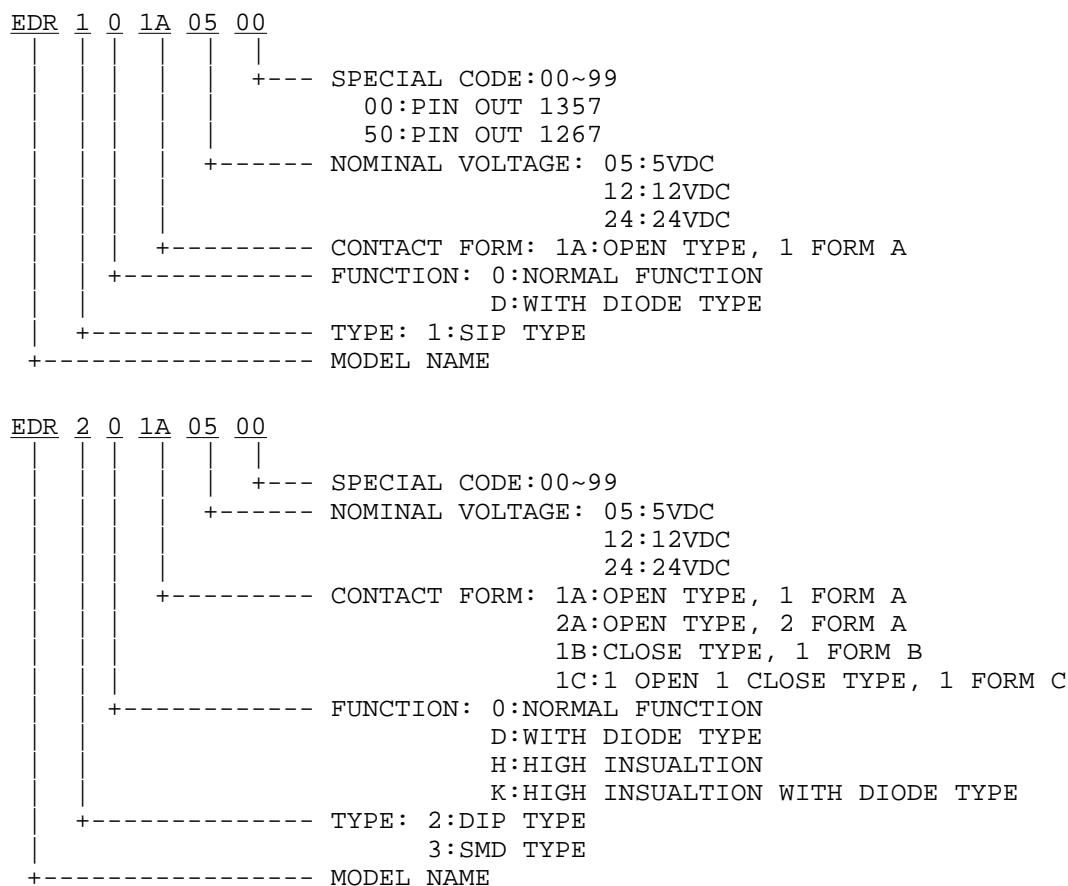
| Contact form | Nominal Voltage(VDC) | Max. Operate Voltage(VDC) | Pull-in Voltage(VDC) | Dropout Voltage(VDC) | ※Coil Resistance(Ω) | Nominal input power(mW) |
|--------------|----------------------|---------------------------|----------------------|----------------------|------------------------------|-------------------------|
| 1A | 5 | 16 | 3.75 | 0.8 | 500±10% | 50 |
| | 12 | 20 | 9.00 | 1.0 | 1000±10% | 144 |
| | 24 | 32 | 18.00 | 2.0 | 2150±10% | 268 |
| 2A | 5 | 11 | 3.75 | 0.8 | 140±10% | 179 |
| | 12 | 20 | 9.00 | 1.0 | 500±10% | 288 |
| | 24 | 32 | 18.00 | 2.0 | 2150±10% | 268 |
| 1B | 5 | 6 | 3.75 | 0.8 | 500±10% | 50 |
| | 12 | 14.5 | 9.00 | 1.0 | 1000±10% | 144 |
| | 24 | 29 | 18.00 | 2.0 | 2150±10% | 268 |
| 1C | 5 | 11 | 3.75 | 0.8 | 200±10% | 125 |
| | 12 | 20 | 9.00 | 1.0 | 500±10% | 288 |
| | 24 | 32 | 18.00 | 2.0 | 2150±10% | 268 |

※Special design are available on request.

● CONTACT RATING

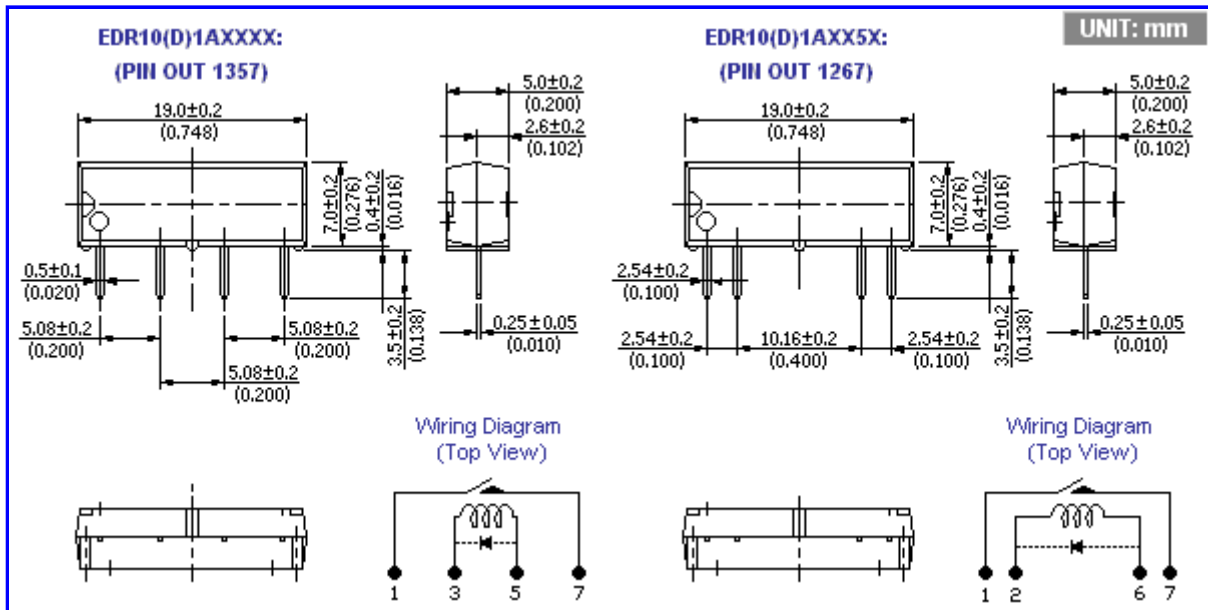
| Contact form | 1A | 2A | 1B | 1C | |
|-----------------------|---|--|---|--|---------------|
| Switching current | 0.5 ADC Max. | 0.5 ADC Max. | 0.5 ADC Max. | 0.2 ADC Max. | |
| Carry current | 1.0 ADC Max. | 1.0 ADC Max. | 1.0 ADC Max. | 0.5 ADC Max. | |
| Switching power | 10 VA Max. | 10 VA Max. | 10 VA Max. | 3 VA Max. | |
| Electrical life | 1x10 ⁸ (Ref 10VDC,10mA) | 1x10 ⁸ (Ref 10VDC,10mA) | 1x10 ⁸ (Ref 10VDC,10mA) | 5x10 ⁷ (Ref 5VDC,1mA) | |
| Contact resistance | 150 mΩ Max. | 150 mΩ Max. | 150 mΩ Max. | 150 mΩ Max. | |
| Operate time | 1.0 ms Max. (including bounce time) | 1.0 ms Max. (including bounce time) | 1.0 ms Max. (including bounce time) | 1.5 ms Max. (including bounce time) | |
| Release time | 0.5 ms Max. | 0.5 ms Max. | 0.5 ms Max. | 2.0 ms Max. | |
| Maximum voltage | 100 VDC Max. | 100 VDC Max. | 100 VDC Max. | 30 VDC Max. | |
| Insulation resistance | 10 ¹⁰ Ω Min. (at 100 VDC) | 10 ¹⁰ Ω Min. (at 100 VDC) | 10 ¹⁰ Ω Min. (at 100 VDC) | 10 ⁹ Ω Min. (at 100 VDC) | |
| Dielectric strength | Coil to contact | 1400 VDC Min. (General) 4000 VDC Min. (High insulation) | 1400 VDC Min. | 1400 VDC Min. | 1400 VDC Min. |
| | Across contacts | 250 VDC Min. | 250 VDC Min. | 250 VDC Min. | 150 VDC Min. |
| Temperature range | Operating temperature | -40℃ ~ +85℃ | -40℃ ~ +85℃ | -40℃ ~ +85℃ | -40℃ ~ +85℃ |
| | Storage temperature | -55℃ ~ +125℃ | -55℃ ~ +125℃ | -55℃ ~ +125℃ | -55℃ ~ +125℃ |
| Shock resistance | 30G Min. | 30G Min. | 30G Min. | 30G Min. | |

PART NUMBERING SYSTEM

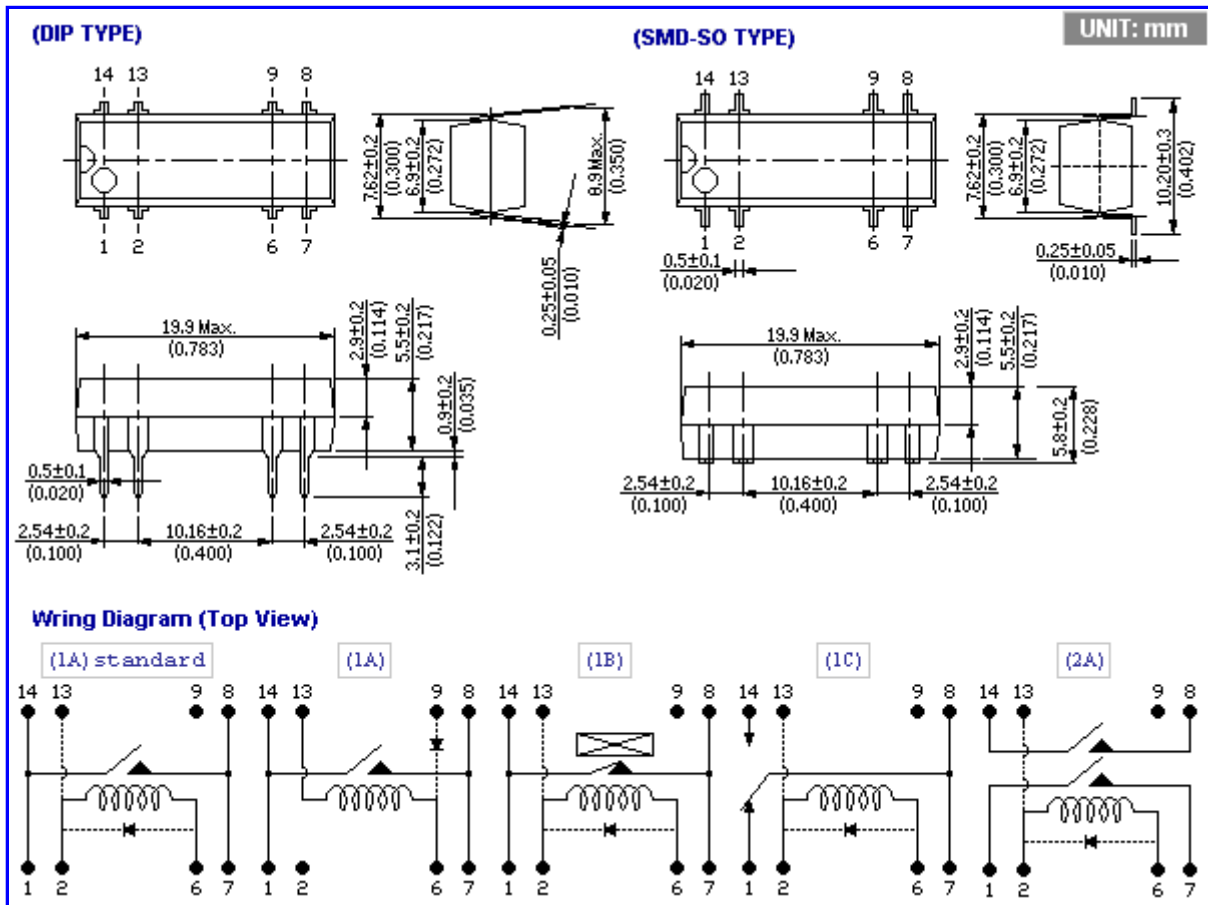


DIMENSIONS

SIP TYPE



DIP TYPE / SMD TYPE



● HIGH INSULATION TYPE

